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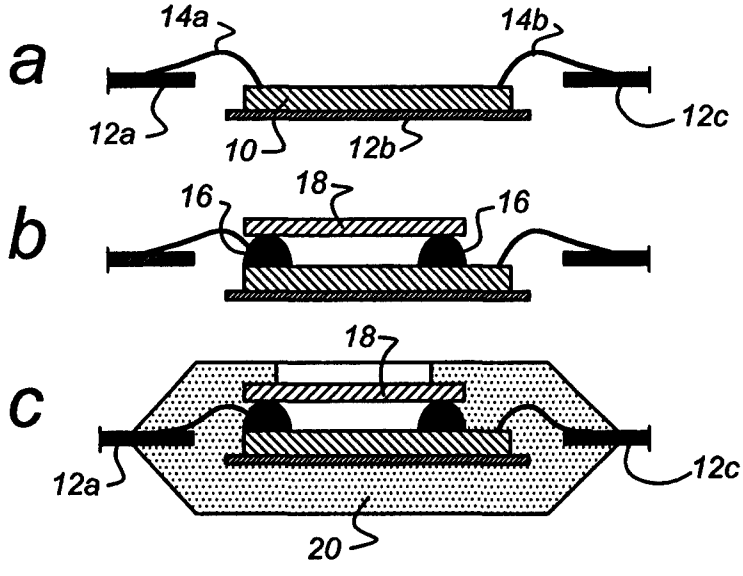
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(54) Title: METHOD FOR ENCAPSULATING A CHIP HAVING A SENSITIVE SURFACE



(57) Abstract: Method for encapsulating a chip having a sensitive surface exposed in a sealed highly clean cavity package, comprising the following steps : a) mounting the chip onto a lead frame, b) bonding the chip contact pads to the lead frame contact pads, c) positioning the chip and lead frame into the one part of a two part mould d), taking measures to keep the space above the sensitive surface of the chip free during the encapsulation process, e) closing the mould by placing the second part thereof on top of the above-mentioned one part, f) introducing the package material into the mould and providing the circumstances to let the package cure in the desired manner. The above-mentioned measures in step d) comprise : d1) applying a closed dam of heat resistant material around the sensitive chip area, d2) placing a lid on said dam such that space above the sensitive area enclosed by said dam and said lid is sealed.

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